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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	47
Program Memory Size	96КВ (96К х 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	52-LQFP
Supplier Device Package	52-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2135acnfp-30

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1.3 Block Diagram

Figure 1.2 shows a Block Diagram.



Figure 1.2 Block Diagram



1.4 Pin Assignment

Figure 1.3 shows the Pin Assignment (Top View). Tables 1.4 and 1.5 outline the Pin Name Information by Pin Number.





			I/O Pin Functions for Peripheral Modules					
Pin Number	Control Pin	Port	Interrupt	Timer	Serial Interface	SSU	I ² C bus	A/D Converter, D/A Converter, Comparator B
1		P5_6		(TRAO)				
2		P3_2	(INT1/INT2)	(TRAIO)				
3		P3_0	,	(TRAO)				
4		P4_2						VREF
5	MODE							
6	(XCIN)	P4_3						
7	(XCOUT)	P4_4						
8	RESET							
9	XOUT	P4_7						
10	VSS/AVSS							
11	XIN	P4_6						
12	VCC/AVCC							
13		P3_7		TRAO	(RXD2/SCL2/ TXD2/SDA2)	SSO	SDA	
14		P3_5		(TRCIOD)	(CLK2)	SSCK	SCL	
15		P3_4		(TRCIOC)	(RXD2/SCL2/ TXD2/SDA2)	SSI		IVREF3
16		P3_3	INT3	(TRCCLK)	(CTS2/RTS2)	SCS		IVCMP3
17		P2_7		(TRDIOD1)				
18		P2_6		(TRDIOC1)				
19		P2_5		(TRDIOB1)				
20		P2_4		(TRDIOA1)				
21		P2_3		(TRDIOD0)				
22		P2_2		(TRCIOD/ TRDIOB0)				
23		P2_1		(TRCIOC/ TRDIOC0)				
24		P2_0	(INT1)	(TRCIOB/ TRDIOA0/ TRDCLK)				
25		P3_6	(INT1)					
26		P3_1		(TRBO)				
27		P6_7	(INT3)	(TRCIOD)				
28		P6_6	INT2	(TRCIOC)	(TXD2/SDA2)			
29		P6_5	INT4	(TRCIOB)	(CLK1/CLK2)			
30		P4_5	INTO		(RXD2/SCL2)			ADTRG
31		P1_7	INT1	(TRAIO)				IVCMP1
32		P1_6			(CLK0)			IVREF1
33		P1_5	(INT1)	(TRAIO)	(RXD0)			
34		P1_4	,	(TRCCLK)	(TXD0)			
35		P1_3	KI3	TRBO (/TRCIOC)				AN11

Table 1.4	Pin Name Information by Pin Number (1)
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Note:

1. Can be assigned to the pin in parentheses by a program.



1.5 Pin Functions

Tables 1.6 and 1.7 list Pin Functions.

Table 1.6Pin Functions (1)

Item	Pin Name	I/O Type	Description
Power supply input	VCC, VSS	-	Apply 1.8 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	-	Power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset input	RESET	I	Input "L" on this pin resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
XIN clock input	XIN	I	These pins are provided for XIN clock generation circuit I/O. Connect a ceramic resonator or a crystal oscillator between
XIN clock output	XOUT	I/O	the XIN and XOUT pins ⁽¹⁾ . To use an external clock, input it to the XOUT pin and leave the XIN pin open.
XCIN clock input	XCIN	Ι	These pins are provided for XCIN clock generation circuit I/O. Connect a crystal oscillator between the XCIN and XCOUT
XCIN clock output	XCOUT	0	pins ⁽¹⁾ . To use an external clock, input it to the XCIN pin and leave the XCOUT pin open.
INT interrupt input	INT0 to INT4	I	INT interrupt input pins. INT0 is timer RB, RC and RD input pin.
Key input interrupt	KI0 to KI3	I	Key input interrupt input pins
Timer RA	TRAIO	I/O	Timer RA I/O pin
	TRAO	0	Timer RA output pin
Timer RB	TRBO	0	Timer RB output pin
Timer RC	TRCCLK	I	External clock input pin
limer RC	TRCTRG	I	External trigger input pin
	TRCIOA, TRCIOB, TRCIOC, TRCIOD	I/O	Timer RC I/O pins
Timer RD	TRDIOA0, TRDIOA1, TRDIOB0, TRDIOB1, TRDIOC0, TRDIOC1, TRDIOD0, TRDIOD1	I/O	Timer RD I/O pins
	TRDCLK	I	External clock input pin
Timer RE	TREO	0	Divided clock output pin
Serial interface	CLK0, CLK1, CLK2	I/O	Transfer clock I/O pins
	RXD0, RXD1, RXD2	I	Serial data input pins
	TXD0, TXD1, TXD2	0	Serial data output pins
	CTS2	I	Transmission control input pin
	RTS2	0	Reception control output pin
	SCL2	I/O	I ² C mode clock I/O pin
	SDA2	I/O	I ² C mode data I/O pin
I ² C bus	SCL	I/O	Clock I/O pin
	SDA	I/O	Data I/O pin
SSU	SSI	I/O	Data I/O pin
	SCS	I/O	Chip-select signal I/O pin
	SSCK	I/O	Clock I/O pin
	SSO	I/O	Data I/O pin

I: Input O: Output I/O: Input and output

Note:

1. Refer to the oscillator manufacturer for oscillation characteristics.



2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 to R3. R0 can be split into high-order bits (R0H) and low-order bits (R0L) to be used separately as 8-bit data registers. R1H and R1L are analogous to R0H and R0L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). R3R1 is analogous to R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer, arithmetic, and logic operations. A1 is analogous to A0. A1 can be combined with A0 and as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the starting address of an interrupt vector table.

2.5 Program Counter (PC)

PC is 20 bits wide and indicates the address of the next instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointers (SP), USP and ISP, are each 16 bits wide. The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is an 11-bit register indicating the CPU state.

2.8.1 Carry Flag (C)

The C flag retains carry, borrow, or shift-out bits that have been generated by the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debugging only. Set it to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation results in 0; otherwise to 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value; otherwise to 0.

2.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is set to 1.

2.8.6 Overflow Flag (O)

The O flag is set to 1 when an operation results in an overflow; otherwise to 0.



2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts.

Interrupts are disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1. The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns processor interrupt priority levels from level 0 to level 7. If a requested interrupt has higher priority than IPL, the interrupt is enabled.

2.8.10 Reserved Bit

If necessary, set to 0. When read, the content is undefined.



3. Memory

3.1 R8C/35C Group

Figure 3.1 is a Memory Map of R8C/35C Group. The R8C/35C Group has a 1-Mbyte address space from addresses 00000h to FFFFh. The internal ROM (program ROM) is allocated lower addresses, beginning with address 0FFFFh. For example, a 32-Kbyte internal ROM area is allocated addresses 08000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. The starting address of each interrupt routine is stored here.

The internal ROM (data flash) is allocated addresses 03000h to 03FFFh.

The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 2.5-Kbyte internal RAM area is allocated addresses 00400h to 00DFFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh and 02C00h to 02FFFh. Peripheral function control registers are allocated here. All unallocated spaces within the SFRs are reserved and cannot be accessed by users.



Figure 3.1 Memory Map of R8C/35C Group

Address	Register	Symbol	After Reset
00C0h	A/D Register 0	AD0	XXh
00C1h			00000XXb
00C2h	A/D Register 1	AD1	XXh
00C3h			000000XXb
00C4h	A/D Register 2	AD2	XXh
00C5h			000000XXb
00C6h	A/D Register 3	AD3	XXh
00C7h			00000XXb
00C8h	A/D Register 4	AD4	XXh
00C9h			000000XXb
00CAh	A/D Register 5	AD5	XXh
00CBh		100	000000XXb
0000Dh	A/D Pagistor 6	AD6	XXh
00000h	A/D Register 0	ADU	000000226
00CDN	A/D Bogistor 7		
00CEh	A/D Register 7	ADT	200000XXF
OUCFN			dXX000000
00D0h			
00D1h			
00D2h			
00D3h			0.01
00D4h	A/D Mode Register	ADMOD	UUh
00D5h	A/D Input Select Register	ADINSEL	1100000b
00D6h	A/D Control Register 0	ADCON0	00h
00D7h	A/D Control Register 1	ADCON1	00h
00D8h	D/A0 Register	DA0	00h
00D9h	D/A1 Register	DA1	00h
00DAh			
00DBh			
00DCh	D/A Control Register	DACON	00h
00DDh	g		
00DEh			
00DEh			
00E0b	Port PO Register	PO	XXb
00E1h	Port P1 Pogister	D1	XXh
00E2h	Port P0 Direction Register		00b
00E2h	Port P1 Direction Register		00h
00E3H	Port P2 Degister		
00E4N	Port P2 Register	P2	
00E50	Port P3 Register	P3	AAN 00h
00E6N	Port P2 Direction Register	PD2	000
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXn
00E9h	Port P5 Register	P5	XXh
00EAh	Port P4 Direction Register	PD4	00h
00EBh	Port P5 Direction Register	PD5	00h
00ECh	Port P6 Register	P6	XXh
00EDh			
00EEh	Port P6 Direction Register	PD6	00h
00EFh			
00F0h			
00F1h			
00F2h			
00F3h			
00F4h			
00F5h			
00F6h			
00F7h			
00F8h			
00E0h			
00546			
UUFCh			
OUFDh			
00FEh			
00FFh			

Table 4.4SFR Information (4) (1)

X: Undefined

Note: 1. The blank areas are reserved and cannot be accessed by users.



Address	Register	Symbol	After Reset
2C70h	DTC Control Data 6	DTCD6	XXh
2C71h			XXh
2C72h			XXh
2C73h			XXh
2070h			XXh
2074n			XXh
207511			
20760			AAn
2C77h			XXh
2C78h	DTC Control Data 7	DTCD7	XXh
2C79h			XXh
2C7Ah			XXh
2C7Bh			XXh
2C7Ch			XXh
2C7Dh			XXh
2C7Eh			XXh
2C7Fh			XXh
2C80h	DTC Control Data 8	DTCD8	XXh
2000h		DTODO	XXh
200111			XXII XXb
200211			XXh
2083N			
2084h			7.XU
2C85h			XXN
2C86h			XXh
2C87h			XXh
2C88h	DTC Control Data 9	DTCD9	XXh
2C89h			XXh
2C8Ah			XXh
2C8Bh			XXh
2C8Ch			XXh
2C8Dh			XXh
2005h			XXh
200Eh			XXh
2000h	DTC Control Data 10	DTCD10	
20901		DICDIO	
20910			
2C92h			XXn
2C93h			XXh
2C94h			XXh
2C95h			XXh
2C96h			XXh
2C97h			XXh
2C98h	DTC Control Data 11	DTCD11	XXh
2C99h			XXh
2C9Ah			XXh
2C9Bh			XXh
2C9Ch			XXh
2C9Dh			XXh
2C9Eh			XXh
20366			XXh
203111	DTC Control Data 12	DTCD12	XXh
204011	DTO CONTO Data 12		
20A111			
2CA2h			7.XU
2CA3h			7.XU
2CA4h			XXh
2CA5h			XXh
2CA6h			XXh
2CA7h			XXh
2CA8h	DTC Control Data 13	DTCD13	XXh
2CA9h			XXh
2CAAh			XXh
2CABh			XXh
2CACh			XXh
2CADh			XXh
20001			YYh
			VVh
ZUAFN			AA(1

SFR Information (10)⁽¹⁾ Table 4.10

X: Undefined Note: 1. The blank areas are reserved and cannot be accessed by users.



Address	Register	Symbol	After Reset
2CB0h	DTC Control Data 14	DTCD14	XXh
2CB1h		-	XXh
2CB2h			XXh
200211			XXII
2CB3N			XXn
2CB4h			XXh
2CB5h			XXh
2CB6h			XXh
2CB7h			XXh
2007h	DTC Control Data 15	DTCD15	XXh
2000h	DIC Control Data 15	DICDIS	
20090			XAN
2CBAh			XXh
2CBBh			XXh
2CBCh			XXh
2CBDh			XXh
2CBFh			XXh
2CBEb			XXh
2001 h	DTC Control Data 16	DTCD16	XXh
20001		DICDI6	
2001h			XXn
2CC2h			XXh
2CC3h			XXh
2CC4h			XXh
2CC5h			XXh
2006h			XXh
200011			XXb
200711	DTO Ocartasi Data 47	DTOD47	
2008h	DIC Control Data 17	DICDI7	XXn
2CC9h			XXh
2CCAh			XXh
2CCBh			XXh
2CCCh			XXh
2CCDh			XXh
2CCEh			XXh
200Eh			YVh
2001 h	DTC Control Data 18		XXh
20001		DICDI8	
2CD1h			XXN
2CD2h			XXh
2CD3h			XXh
2CD4h			XXh
2CD5h			XXh
2CD6h			XXh
2CD7h			XXh
2007h	DTC Control Data 10	DTCD10	YYh
20000		010013	VVb
20090			
2CDAh			7.XU
2CDBh			XXh
2CDCh			XXh
2CDDh			XXh
2CDEh			XXh
2CDFh			XXh
2051H	DTC Control Data 20	DTCD20	XXh
20101		010020	VVh
20E111			
2CE2h			7.XU
2CE3h			XXh
2CE4h			XXh
2CE5h			XXh
2CE6h			XXh
2CE7h			XXh
2000	DTC Control Data 21	DTCD21	XXb
20501		010021	
20E9n			
2CEAh			XXh
2CEBh			XXh
2CECh			XXh
2CEDh			XXh
2CFFh			XXh
20EEb			XXb
206111		1	7770

SFR Information (11)⁽¹⁾ Table 4.11

X: Undefined Note: 1. The blank areas are reserved and cannot be accessed by users.



Table 4.12	SFR Information	(12) ⁽¹⁾
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Address	Register	Symbol	After Reset
2CF0h	DTC Control Data 22	DTCD22	XXh
2CF1h			XXh
2CF2h			XXh
2CF3h			XXh
2CF4h			XXh
2CF5h			XXh
2CF6h			XXh
2CF7h			XXh
2CF8h	DTC Control Data 23	DTCD23	XXh
2CF9h			XXh
2CFAh			XXh
2CFBh			XXh
2CFCh			XXh
2CFDh			XXh
2CFEh			XXh
2CFFh			XXh
2D00h			
:			-
2FFFh			

2FFFh

X: Undefined

Note: 1. The blank areas are reserved and cannot be accessed by users.

Table 4.13 ID Code Areas and Option Function Select Area

Address	Area Name	Symbol	After Reset
:		·	
FFDBh	Option Function Select Register 2	OFS2	(Note 1)
:			
FFDFh	ID1		(Note 2)
:			
FFE3h	ID2		(Note 2)
:			
FFEBh	ID3		(Note 2)
:			
FFEFh	ID4		(Note 2)
:			
FFF3h	ID5		(Note 2)
:			
FFF/h	ID6		(Note 2)
:			
FFFBh	זטו		(Note 2)
:		050	
FFFFh	Option Function Select Register	OFS	(Note 1)

Notes:

The option function select area is allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program. Do not write additions to the option function select area. If the block including the option function select area is erased, the option function select 1. area is set to FFh.

When blank products are shipped, the option function select area is set to FFh. It is set to the written value after written by the user.

When blank products are shipped, the option function select area is set to FFh. This is set to the written value area written by the user.
The ID code areas are allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program. Do not write additions to the ID code areas. If the block including the ID code areas is erased, the ID code areas are set to FFh. When blank products are shipped, the ID code areas are set to FFh. They are set to the written value after written by the user. When factory-programming products are shipped, the value of the ID code areas is the value programmed by the user.





Figure 5.1 Ports P0 to P6 Timing Measurement Circuit



Symbol	Baramator	Conditions		Lloit		
Symbol	Falameter	Conditions	Min.	Тур.	Max.	Offic
-	Program/erase endurance (2)		1,000 ⁽³⁾	-	-	times
-	Byte program time		-	80	500	μs
-	Block erase time		-	0.3	-	S
td(SR-SUS)	Time delay from suspend request until suspend		-	-	5+CPU clock × 3 cycles	ms
-	Interval from erase start/restart until following suspend request		0	_	_	μS
_	Time from suspend until erase restart		_	_	30+CPU clock × 1 cycle	μS
td(CMDRST- READY)	Time from when command is forcibly terminated until reading is enabled		-	-	30+CPU clock × 1 cycle	μS
—	Program, erase voltage		2.7	_	5.5	V
-	Read voltage		1.8	-	5.5	V
_	Program, erase temperature		0	-	60	°C
-	Data hold time (7)	Ambient temperature = 55°C	20	-	_	year

Table 5.6 Flash Memory (Program ROM) Electrical Characteristics

Notes: 1. Vcc = 2.7 to 5.5 V and $T_{opr} = 0$ to 60°C, unless otherwise specified.

2. Definition of programming/erasure endurance

The programming and erasure endurance is defined on a per-block basis. If the programming and erasure endurance is n (n = 1,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.

However, the same address must not be programmed more than once per erase operation (overwriting prohibited).

3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed). 4. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.

5. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.

6. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.

7. The data hold time includes time that the power supply is off or the clock is not supplied.



Symbol	Baramatar		Condition		St	Linit		
Symbol		Parameter	Condition		Min.	Тур.	Max.	Unit
Vон	Output "H"	Other than XOUT	Drive capacity High Vcc = 5 V	Iон = -20 mA	Vcc - 2.0	-	Vcc	V
	voltage		Drive capacity Low Vcc = 5 V	Iон = -5 mA	Vcc - 2.0	-	Vcc	V
		XOUT	Vcc = 5 V	Іон = -200 μА	1.0	-	Vcc	V
Vol	Output "L"	Other than XOUT	Drive capacity High $Vcc = 5 V$	IoL = 20 mA	-	-	2.0	V
	voltage		Drive capacity Low Vcc = 5 V	lo∟ = 5 mA	-	-	2.0	V
		XOUT	Vcc = 5 V	IoL = 200 μA	-	-	0.5	V
VT+-VT-	Hysteresis	INTO, INT1, INT2, INT3, INT4, KI0, KI1, KI2, KI3, TRAIO, TRBO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRDIOA0, TRDIOB0, TRDIOC0, TRDIOD0, TRDIOA1, TRDIOD1, TRDIOC1, TRDIOD1, TRCTRG, TRCCLK, ADTRG, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO			0.1	1.2	_	V
		RESET			0.1	1.2	-	V
Іін	Input "H" cu	rrent	VI = 5 V, Vcc = 5.0 V		-	-	5.0	μΑ
lı∟	Input "L" cu	rrent	VI = 0 V, Vcc = 5.0 V		-	-	-5.0	μΑ
Rpullup	Pull-up resistance		VI = 0 V, Vcc = 5.0 V		25	50	100	kΩ
Rfxin	Feedback resistance	XIN			-	0.3	_	MΩ
Rfxcin	Feedback resistance	XCIN			-	8	-	MΩ
VRAM	RAM hold v	oltage	During stop mode		1.8	-	-	V

Table 5.17	Electrical	Characteristics	(1) [4.2	$2 V \le Vcc$	≤ 5.5 V]
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Note:

1. $4.2 \text{ V} \le \text{Vcc} \le 5.5 \text{ V}$ and $\text{T}_{opr} = -20 \text{ to } 85^{\circ}\text{C}$ (N version) / -40 to 85°C (D version), f(XIN) = 20 MHz, unless otherwise specified.



Timing Requirements (Unless Otherwise Specified: Vcc = 5 V, Vss = 0 V at Topr = 25°C)

Table 5.19 External Clock Input (XOUT, XCIN)

Symbol	Parameter		Standard		
			Max.	Offic	
tc(XOUT)	XOUT input cycle time	50	-	ns	
twh(xout)	XOUT input "H" width	24	-	ns	
twl(xout)	XOUT input "L" width	24	-	ns	
tc(XCIN)	XCIN input cycle time	14	-	μS	
twh(xcin)	XCIN input "H" width	7	-	μS	
twl(xcin)	XCIN input "L" width	7	-	μS	



Figure 5.8 External Clock Input Timing Diagram when VCC = 5 V

Table 5.20 TRAIO Input

Symbol	Parameter		Standard		
			Max.	Onit	
tc(TRAIO)	TRAIO input cycle time	100	-	ns	
twh(traio)	TRAIO input "H" width	40	-	ns	
twl(traio)	TRAIO input "L" width	40	-	ns	



Figure 5.9 TRAIO Input Timing Diagram when Vcc = 5 V



Symbol	Parameter		Standard		
			Max.	Ofine	
tc(CK)	CLKi input cycle time	200	-	ns	
tW(CKH)	CLKi input "H" width	100	-	ns	
tW(CKL)	CLKi input "L" width	100	-	ns	
td(C-Q)	TXDi output delay time	-	50	ns	
th(C-Q)	TXDi hold time	0	-	ns	
tsu(D-C)	RXDi input setup time	50	-	ns	
th(C-D)	RXDi input hold time	90	-	ns	

i = 0 to 2



Figure 5.10 Serial Interface Timing Diagram when Vcc = 5 V

Table 5.22 External Interrupt \overline{INTi} (i = 0 to 4) Input, Key Input Interrupt \overline{KIi} (i = 0 to 3)

Symbol Parameter	Parameter		Standard		
	Min.	Max.	Unit		
tw(INH)	INTi input "H" width, Kli input "H" width	250 (1)	-	ns	
tw(INL)	INTi input "L" width, Kli input "L" width	250 ⁽²⁾	-	ns	

Notes:

1. When selecting the digital filter by the INTi input filter select bit, use an INTi input HIGH width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.

2. When selecting the digital filter by the INTi input filter select bit, use an INTi input LOW width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.





Timing Requirements (Unless Otherwise Specified: Vcc = 3 V, Vss = 0 V at Topr = 25°C)

Table 5.25 External Clock Input (XOUT, XCIN)

Symbol	Parameter		Standard		
			Max.	Unit	
tc(XOUT)	XOUT input cycle time	50	=	ns	
twh(xout)	XOUT input "H" width	24	-	ns	
twl(xout)	XOUT input "L" width	24	-	ns	
tc(XCIN)	XCIN input cycle time	14	-	μS	
twh(xcin)	XCIN input "H" width	7	-	μS	
twL(XCIN)	XCIN input "L" width	7	-	μS	



Figure 5.12 External Clock Input Timing Diagram when VCC = 3 V

Table 5.26 TRAIO Input

Symbol	Parameter		Standard		
			Max.	Unit	
tc(TRAIO)	TRAIO input cycle time	300	-	ns	
twh(traio)	TRAIO input "H" width	120	-	ns	
twl(traio)	TRAIO input "L" width	120	-	ns	



Figure 5.13 TRAIO Input Timing Diagram when Vcc = 3 V



Table 5.30Electrical Characteristics (6) [1.8 V \leq Vcc < 2.7 V]
(Topr = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Condition		Standard	t t	Unit
Cymbol	rarameter		Condition	Min.	Тур.	Max.	Onit
Icc	Power supply current (Vcc = 1.8 to 2.7 V) Single-chip mode,	High-speed clock mode	XIN = 5 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	_	2.2	_	mA
	other pins are Vss		XIN = 5 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	-	0.8	-	mA
		High-speed on-chip oscillator	XIN clock off High-speed on-chip oscillator on fOCO-F = 5 MHz Low-speed on-chip oscillator on = 125 kHz No division	-	2.5	10	mA
		mode	XIN clock off High-speed on-chip oscillator on fOCO-F = 5 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	-	1.7	_	mA
			XIN clock off High-speed on-chip oscillator on fOCO-F = 4 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-16 MSTIIC = MSTTRD = MSTTRC = 1	-	1	-	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR27 = 1, VCA20 = 0	-	90	300	μΑ
		Low-speed clock mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz No division, FMR27 = 1, VCA20 = 0	-	80	350	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz No division, Program operation on RAM Flash memory off, FMSTP = 1, VCA20 = 0	_	40	_	μΑ
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	_	15	90	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	-	4	80	μΑ
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz (peripheral clock off) While a WAIT instruction is executed VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	_	3.5	-	μA
		Stop mode	XIN clock off, Topr = 25°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	_	2.0	5	μA
			XIN clock off, Topr = 85°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1	_	5.0 ⁽¹⁾ 15 ⁽²⁾		μA
			Peripheral clock off VCA27 = VCA26 = VCA25 = 0				

Notes:

1. Value when the program ROM capacity of the product is 16 Kbytes to 32 Kbytes.

2. Value when the program ROM capacity of the product is 48 Kbytes to 128 Kbytes.

Table 5.33 Seri	ial Interface
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Symbol	Parameter		Standard		
			Max.	Unit	
tc(CK)	CLKi input cycle time	800	-	ns	
tW(CKH)	CLKi input "H" width	400	-	ns	
tW(CKL)	CLKi input "L" width	400	-	ns	
td(C-Q)	TXDi output delay time	-	200	ns	
th(C-Q)	TXDi hold time	0	-	ns	
tsu(D-C)	RXDi input setup time	150	-	ns	
th(C-D)	RXDi input hold time	90	-	ns	

i = 0 to 2



Figure 5.18 Serial Interface Timing Diagram when Vcc = 2.2 V

Table 5.34 External Interrupt INTi (i = 0 to 4) Input, Key Input Interrupt Kli (i = 0 to 3)

Symbol	Parameter		Standard		
Symbol	Falallielei	Min.	Max.	Unit	
tw(INH)	INTi input "H" width, Kli input "H" width	1000 (1)	-	ns	
tw(INL)	INTi input "L" width, Kli input "L" width	1000 (2)	-	ns	

Notes:

1. When selecting the digital filter by the INTi input filter select bit, use an INTi input HIGH width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.

2. When selecting the digital filter by the INTi input filter select bit, use an INTi input LOW width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.



Figure 5.19 Input Timing Diagram for External Interrupt \overline{INTi} and Key Input Interrupt \overline{Kli} when Vcc = 2.2 V

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Rev.	Date	Description	
		Page	Summary
0.10	Sep. 01, 2009	-	First Edition issued
1.00	Aug. 24, 2010	All	"Preliminary" and "Under development" deleted
		4	Table1.3 revised
		27 to 53	5. Electrical Characteristics added

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